

IN THE CLAIMS:

Claims 1-23 (Canceled).

24. (Currently Amended) A method of manufacturing a circuit board comprising a plurality of wiring patterns each extending across a surface of an insulating substrate for connecting at least two locations on the substrate, and a plurality of protrusions located at desired locations on the wiring patterns, the method comprising:

simultaneously and unitarily forming the wiring patterns and the protrusions, and

~~modifying the protrusions to have substantially equal heights.~~

25. (Previously Amended) The method of manufacturing a circuit board as defined in Claim 24, wherein the wiring patterns and the protrusions are made of a same conductive sintered material.

Claims 26-28 (Withdrawn).

29. (Currently Amended) A method of manufacturing a semiconductor device comprising the steps of:

simultaneously and unitarily forming a first plurality of wiring patterns and a second plurality of protrusions located at desired locations on the wiring patterns on an insulating substrate, the protrusions having substantially equal heights, the wiring patterns each extending across a surface of the substrate for connecting at least two locations on the substrate;

modifying the protrusions to have substantially equal heights; and

coupling electrically the protrusions and electrodes disposed on a semiconductor chip component.

Serial No.: 09/754,133

30. (Previously Amended) The method of manufacturing a semiconductor device as defined in Claim 29, wherein the wiring patterns and the protrusions are made of a same conductive sintered material.

*D*  
Claims 31-34 (Withdrawn).

35. (New) The method of manufacturing a circuit board as defined in claim 24, further comprising modifying the protrusions to have substantially equal heights.

36. (New) The method of manufacturing a circuit board as defined in claim 35, wherein said modifying comprises imposing a load on said protrusions.